

BOM Change Summary

▶ ADSP-21060L, ADSP-21061L and ADSP-21160M

Assembly Site	STATS Singapore - STA (From)	ASE Taiwan – AET (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	Ablestik 2000 conductive	AB-2100 Conductive
Mold Compound	Sumitomo G770	Hitachi CEL-9750
Ball Size	0.75	0.75
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

▶ ADSP-21160N

Assembly Site	STATS Singapore - STA (From)	ASE Taiwan – AET (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	Ablestik 2000 conductive	AB-2100 Conductive
Mold Compound	Sumitomo G770	Hitachi CEL-9750
Ball Size	0.75	0.75
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

▶ ADSP-BF561

Assembly Site	STATS Singapore - STA (From)	ASE Taiwan – AET (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	Ablestik 2000 conductive	AB-2100 Conductive
Mold Compound	Sumitomo G770	Hitachi CEL-9750
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

▶ ADSP-TS101S

Assembly Site	STATS Singapore - STA (From)	ASE Taiwan – AET (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	Ablestik 2000 conductive	AB-2100 Conductive
Mold Compound	Sumitomo G770	Hitachi CEL-9750
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu